

MECHANICAL CASE OUTLINE

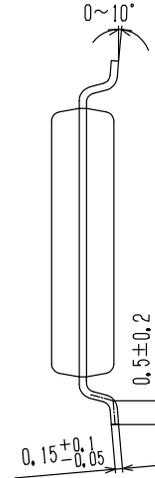
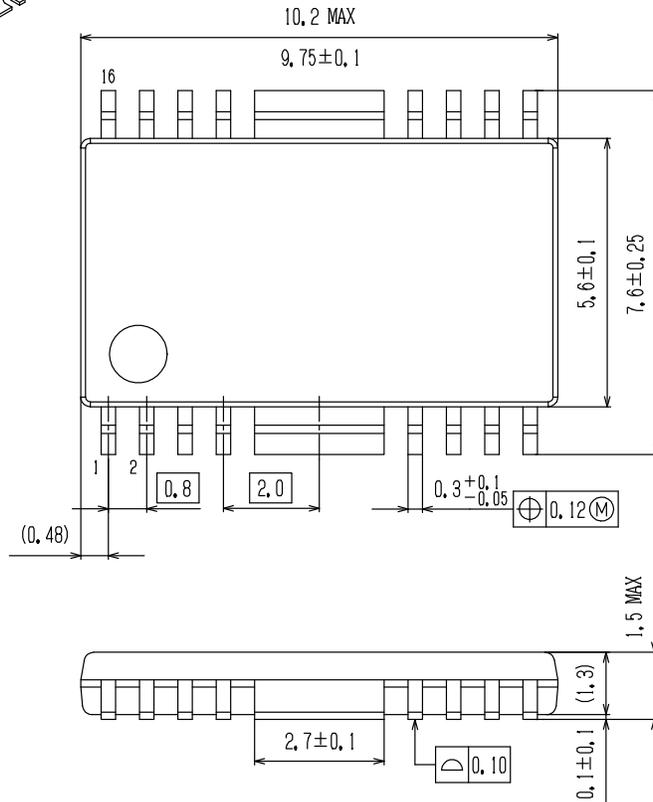
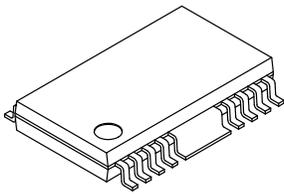
PACKAGE DIMENSIONS

ON Semiconductor®

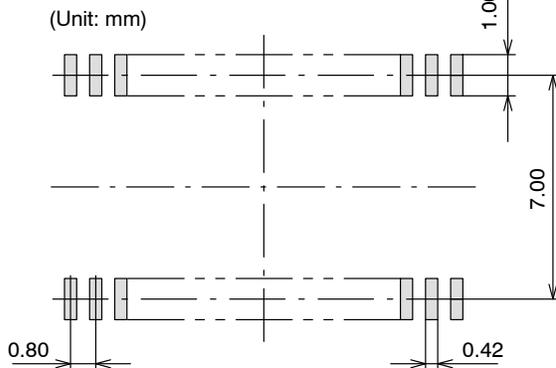


HSSOP16 (275 mil) CASE 943AF ISSUE A

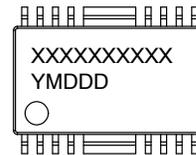
DATE 25 OCT 2013



SOLDERING FOOTPRINT*



GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

NOTE: The measurements are not to guarantee but for reference only.
 Land pattern design in Fin area to be altered in response to customers' individual application.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking.
 Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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